



EEPC India Invites Participation For India Pavilion at FENCETECH 2012, Miami Beach, Florida, USA

(25 - 27 January, 2012)

FENCETECH 2012 is the largest Fence, Deck, Railing and Security show in North America Organized by American Fence Association (AFA), FENCETECH brings together industry's leading manufacturers, distributors and contractors to showcase the latest innovations in the fence industry. Scheduled during 25th January to 27th January, 2012 at Miami Beach Convention Centre, Miami, this show is also known as AFA's annual convention and trade show.

FENCETECH 2012 will witness participation by professional from agricultural products, construction drawing software, hand held specialty tools, home & garden and welding equipment industries.

EEPC India is organizing an India Pavilion at **FENCETECH 2012 and invites applications from its members** to participate in the show.

It will provide an excellent platform for the Indian exhibitors to showcase their products, meet industry professionals and explore the latest innovations in the fencing market. Growth potential for Indian manufacturers/exporters is significant in the North American fencing market.

Product Category

The following products/areas would be covered in the exhibition:

- Access Control Devices
- Concrete/Cement Mixers Post Setting Equipment
- Chain-Link Fence & Accessories
- Composite Products & Accessories
- Deck & Railing Materials & Accessories
- Farm/Ranch Fence Materials
- Fence Fillers/Inserts
- Fittings
- Gates & Associated Products
- Gate Operators & Associated Products
- High Security
- Highway Fence Products
- Machinery/Equipment for Installation
- Machinery/Equipment for Manufacturing
- Ornamental Fence
- Paints, Coatings, Sealants
- Pipe & Tubing
- PVC, Vinyl/Plastic Fence
- Playground Equipment/Supplies
- Pool Safety Systems
- Post Caps, Finials
- Security Fence & Access Controls
- Signs
- Snow Fence
- Software/Computers
- Sports Fence & Accessories
- Tools/Power Tools
- Trucks (pickup)
- Wood Fence Materials & Accessories

Venue

Miami Beach Convention Center, Miami Beach, Florida, USA

Date

25 - 27th January, 2012 (3 days)

Participation Charges

Built-up booth (Non-island space 8" high

Back drape and 3" high side dividers)

(Minimum 100 sq. ft. booth)

: US\$ 28 per sq. ft. or Indian ₹ 1,400 per sq. ft.

+ ₹ 144.20 per sq. ft. as deposit towards Service Tax.

If participants make payments in US\$, then Service Tax is not applicable.

If participation charges are paid in INR an amount equivalent to the corresponding Service Tax amount is also to be added which shall be treated as a deposit pending clarification from the authorities.



Mode of Payment

Full payment is to be made by :

- ❖ Swift Transfer in US Dollar (**to add US\$ 50 per remittance to offset bank charges etc.**) as per following details :

Name of the Bank : HDFC BANK LTD
Address of the Bank : Central Plaza, 2/6 Sarat Bose Road
Kolkata - 700 020
Branch Code : 0014
Account Number : 00148580000013
Beneficiary Name : EEPC INDIA
SWIFT Code : HDFCINBBCAL

THROUGH :

JP MORGAN CHASE BANK, NEW YORK
A/c. No. 001-1-406717
SWIFT Code – CHASUS33
CHIPS ABA : 0002
FEDWIRE ABA : 021000021
CHIPS UID # 354459

Display Booth

There will be in-built display booths of 100 sq. ft. each. EEPC India will provide the following:

- Carpeted Floor
- One 4' Table (Draped)
- One Cabinet
- Two Chairs
- Three Spot Lights
- One Plug Socket
- One Wastepaper Basket
- Fascia

Date of Payment

Full payment is to be made along with the **Application Form** latest by **15th November, 2011**. Payment may be made by Demand Draft/at par Cheque drawn in favour of “**EEPC INDIA**”.

Cancellation of Participation

Request for cancellation of participation will not be entertained after the confirmation. Any cancellation after the confirmation shall result in forfeiture of the amount already paid on this account. In addition, the participating company shall be liable to make the full booth cost.

Benefit for the member-exporters

EEPC INDIA is organizing this event under the MAI Scheme of Ministry of Commerce & Industry, Government of India. Therefore no MDA grant would be available. The rates mentioned above are subsidized as per MAI Scheme of Government of India.



Submission of Application

Interested firms may please send the **Application Form**, duly filled in and signed, along with full payment **latest by 15th November, 2011** to the respective Regional Offices or to:

Shri R. Maitra

Executive Director

EEPC INDIA

Vandhna (4th Floor)

11, Tolstoy Marg

New Delhi – 110 001

Tel. : 91-11-23353353, 23711124/25

Fax : 91-11-23310920

E-mail : eepcto@eepcindia.net

Shri B. Sarkar

Addl. Executive Director & Secretary

EEPC INDIA

Vanijya Bhavan (1st Floor), ITFC

1/1 Wood Street

Kolkata - 700 016

Tel. : 91-33-22890651/52/53

Fax : 91-33-22890654

E-mail : eepcho@eepcindia.net



Application Form
India Pavilion at FENCETECH 2012
(25 - 27 January, 2012)

Name of the Company	:			
Postal Address	:			
Phone (with area code)	:			
Fax (with area code)	:			
E-mail	:			
Website	:			
Name & Designation of the Chief Executive	:			
Name & Designation of the Participants	:			
Space required (in sq. mtr.)	:			
PAN No. of the Company	:			
TAN No. of the Company	:			
Type of Units	:	<input type="checkbox"/> SSI	<input type="checkbox"/> Non-SSI	
Status	:	<input type="checkbox"/> Manufacturer/Exporter	<input type="checkbox"/> Merchant Exporter	
		<input type="checkbox"/> Export House		
Total Annual Export (in Million US\$)	:	2008-2009	2009-2010	2010-2011
Total Export to USA (in Million US\$)	:	2008-2009	2009-2010	2010-2011
Foreign Collaboration, if any	:			
Products Manufactured/Exported	:			
Countries of Export	:			
Accreditation to International Standards (like ISO, QS)	:			
Nature of Display	:	Display of Samples	<input type="checkbox"/>	
		Display of Posters	<input type="checkbox"/>	

Please use separate sheet to furnish details of your company (within 80 words) for the Exhibitors' Profile. Please send us this Form duly filled-in and signed along with full payment by Demand Draft and 2 (two) copies of passport size colour photographs of the Participant.

Signature :

Date :

Office Seal :